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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	66MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (2), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 95°C (TJ)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc860dtvr66d4

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Overview

1 Overview

The MPC860 power quad integrated communications controller (PowerQUICCTM) is a versatile one-chip integrated microprocessor and peripheral combination designed for a variety of controller applications. It particularly excels in communications and networking systems. The PowerQUICC unit is referred to as the MPC860 in this hardware specification.

The MPC860 implements Power ArchitectureTM technology and contains a superset of Freescale's MC68360 quad integrated communications controller (QUICC), referred to here as the QUICC, RISC communications processor module (CPM). The CPU on the MPC860 is a 32-bit core built on Power Architecture technology that incorporates memory management units (MMUs) and instruction and data caches.. The CPM from the MC68360 QUICC has been enhanced by the addition of the inter-integrated controller (I²C) channel. The memory controller has been enhanced, enabling the MPC860 to support any type of memory, including high-performance memories and new types of DRAMs. A PCMCIA socket controller supports up to two sockets. A real-time clock has also been integrated.

Table 1 shows the functionality supported by the MPC860 family.

	Cache ((Kbytes)	Ethe	ernet			
Part	Instruction Cache	Data Cache	10T	10/100	ATM	scc	Reference ¹
MPC860DE	4	4	Up to 2	_	_	2	1
MPC860DT	4	4	Up to 2	1	Yes	2	1
MPC860DP	16	8	Up to 2	1	Yes	2	1
MPC860EN	4	4	Up to 4	_	_	4	1
MPC860SR	4	4	Up to 4	_	Yes	4	1
MPC860T	4	4	Up to 4	1	Yes	4	1
MPC860P	16	8	Up to 4	1	Yes	4	1
MPC855T	4	4	1	1	Yes	1	2

Table 1. MPC860 Family Functionality

Supporting documentation for these devices refers to the following:

^{1.} MPC860 PowerQUICC Family User's Manual (MPC860UM, Rev. 3)

^{2.} MPC855T User's Manual (MPC855TUM, Rev. 1)



2 Features

The following list summarizes the key MPC860 features:

- Embedded single-issue, 32-bit core (implementing the Power Architecture technology) with thirty-two 32-bit general-purpose registers (GPRs)
 - The core performs branch prediction with conditional prefetch without conditional execution.
 - 4- or 8-Kbyte data cache and 4- or 16-Kbyte instruction cache (see Table 1)
 - 16-Kbyte instruction caches are four-way, set-associative with 256 sets; 4-Kbyte instruction caches are two-way, set-associative with 128 sets.
 - 8-Kbyte data caches are two-way, set-associative with 256 sets; 4-Kbyte data caches are two-way, set-associative with 128 sets.
 - Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks.
 - Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
 - MMUs with 32-entry TLB, fully-associative instruction, and data TLBs
 - MMUs support multiple page sizes of 4-, 16-, and 512-Kbytes, and 8-Mbytes; 16 virtual address spaces and 16 protection groups
 - Advanced on-chip-emulation debug mode
- Up to 32-bit data bus (dynamic bus sizing for 8, 16, and 32 bits)
- 32 address lines
- Operates at up to 80 MHz
- Memory controller (eight banks)
 - Contains complete dynamic RAM (DRAM) controller
 - Each bank can be a chip select or RAS to support a DRAM bank.
 - Up to 15 wait states programmable per memory bank
 - Glueless interface to DRAM, SIMMS, SRAM, EPROM, Flash EPROM, and other memory devices
 - DRAM controller programmable to support most size and speed memory interfaces
 - Four \overline{CAS} lines, four \overline{WE} lines, and one \overline{OE} line
 - Boot chip-select available at reset (options for 8-, 16-, or 32-bit memory)
 - Variable block sizes (32 Kbytes to 256 Mbytes)
 - Selectable write protection
 - On-chip bus arbitration logic
- General-purpose timers
 - Four 16-bit timers or two 32-bit timers
 - Gate mode can enable/disable counting
 - Interrupt can be masked on reference match and event capture.



Features

- System integration unit (SIU)
 - Bus monitor
 - Software watchdog
 - Periodic interrupt timer (PIT)
 - Low-power stop mode
 - Clock synthesizer
 - Decrementer, time base, and real-time clock (RTC)
 - Reset controller
 - IEEE 1149.1TM Std. test access port (JTAG)
- Interrupts
 - Seven external interrupt request (IRQ) lines
 - 12 port pins with interrupt capability
 - 23 internal interrupt sources
 - Programmable priority between SCCs
 - Programmable highest priority request
- 10/100 Mbps Ethernet support, fully compliant with the IEEE 802.3u® Standard (not available when using ATM over UTOPIA interface)
- ATM support compliant with ATM forum UNI 4.0 specification
 - Cell processing up to 50–70 Mbps at 50-MHz system clock
 - Cell multiplexing/demultiplexing
 - Support of AAL5 and AAL0 protocols on a per-VC basis. AAL0 support enables OAM and software implementation of other protocols.
 - ATM pace control (APC) scheduler, providing direct support for constant bit rate (CBR) and unspecified bit rate (UBR) and providing control mechanisms enabling software support of available bit rate (ABR)
 - Physical interface support for UTOPIA (10/100-Mbps is not supported with this interface) and byte-aligned serial (for example, T1/E1/ADSL)
 - UTOPIA-mode ATM supports level-1 master with cell-level handshake, multi-PHY (up to four physical layer devices), connection to 25-, 51-, or 155-Mbps framers, and UTOPIA/system clock ratios of 1/2 or 1/3.
 - Serial-mode ATM connection supports transmission convergence (TC) function for T1/E1/ADSL lines, cell delineation, cell payload scrambling/descrambling, automatic idle/unassigned cell insertion/stripping, header error control (HEC) generation, checking, and statistics.
- Communications processor module (CPM)
 - RISC communications processor (CP)
 - Communication-specific commands (for example, GRACEFUL STOP TRANSMIT, ENTER HUNT MODE, and RESTART TRANSMIT)
 - Supports continuous mode transmission and reception on all serial channels



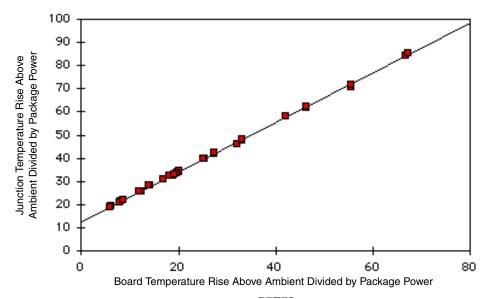


Figure 2. Effect of Board Temperature Rise on Thermal Behavior

If the board temperature is known, an estimate of the junction temperature in the environment can be made using the following equation:

$$T_I = T_B + (R_{\theta IB} \times P_D)$$

where:

 $R_{\theta JB}$ = junction-to-board thermal resistance (°C/W)

 T_B = board temperature (°C)

 P_D = power dissipation in package

If the board temperature is known and the heat loss from the package case to the air can be ignored, acceptable predictions of junction temperature can be made. For this method to work, the board and board mounting must be similar to the test board used to determine the junction-to-board thermal resistance, namely a 2s2p (board with a power and a ground plane) and by attaching the thermal balls to the ground plane.

7.4 Estimation Using Simulation

When the board temperature is not known, a thermal simulation of the application is needed. The simple two-resistor model can be used with the thermal simulation of the application [2], or a more accurate and complex model of the package can be used in the thermal simulation.

7.5 Experimental Determination

To determine the junction temperature of the device in the application after prototypes are available, the thermal characterization parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_{J} = T_{T} + (\Psi_{JT} \times P_{D})$$



Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Max	Unit
В9	CLKOUT to A(0:31), BADDR(28:30), RD/WR, BURST, D(0:31), DP(0:3), TSIZ(0:1), REG, RSV, AT(0:3), PTR High-Z	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B11	CLKOUT to TS, BB assertion	7.58	13.58	6.25	12.25	5.00	11.00	3.80	11.29	ns
B11a	CLKOUT to TA, BI assertion (when driven by the memory controller or PCMCIA interface)	2.50	9.25	2.50	9.25	2.50	9.25	2.50	9.75	ns
B12	CLKOUT to TS, BB negation	7.58	14.33	6.25	13.00	5.00	11.75	3.80	8.54	ns
B12a	CLKOUT to TA, BI negation (when driven by the memory controller or PCMCIA interface)	2.50	11.00	2.50	11.00	2.50	11.00	2.50	9.00	ns
B13	CLKOUT to TS, BB High-Z	7.58	21.58	6.25	20.25	5.00	19.00	3.80	14.04	ns
B13a	CLKOUT to TA, BI High-Z (when driven by the memory controller or PCMCIA interface)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to TEA assertion	2.50	10.00	2.50	10.00	2.50	10.00	2.50	9.00	ns
B15	CLKOUT to TEA High-Z	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	TA, BI valid to CLKOUT (setup time)	9.75	_	9.75	_	9.75	_	6.00	_	ns
B16a	TEA, KR, RETRY, CR valid to CLKOUT (setup time)	10.00	_	10.00	_	10.00	_	4.50	_	ns
B16b	$\overline{BB}, \overline{BG}, \overline{BR},$ valid to CLKOUT (setup time) 5	8.50	_	8.50	_	8.50	_	4.00	_	ns
B17	CLKOUT to \overline{TA} , \overline{TEA} , \overline{BI} , \overline{BB} , \overline{BG} , \overline{BR} valid (hold time)	1.00	_	1.00	_	1.00	_	2.00	_	ns
B17a	CLKOUT to KR, RETRY, CR valid (hold time)	2.00	_	2.00	_	2.00	_	2.00	_	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time) ⁶	6.00	_	6.00	_	6.00	_	6.00	_	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time) ⁶	1.00	_	1.00	_	1.00	_	2.00	_	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time) ⁷	4.00	_	4.00	_	4.00	_	4.00	_	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold time) ⁷	2.00	_	2.00	_	2.00	_	2.00	_	ns
B22	CLKOUT rising edge to $\overline{\text{CS}}$ asserted GPCM ACS = 00	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B22a	CLKOUT falling edge to \overline{CS} asserted GPCM ACS = 10, TRLX = 0	_	8.00	_	8.00	_	8.00	_	8.00	ns
B22b	CLKOUT falling edge to $\overline{\text{CS}}$ asserted GPCM ACS = 11, TRLX = 0, EBDF = 0	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.54	ns
B22c	CLKOUT falling edge to $\overline{\text{CS}}$ asserted GPCM ACS = 11, TRLX = 0, EBDF = 1	10.86	17.99	8.88	16.00	7.00	14.13	5.18	12.31	ns



Table 7. Bus Operation Timings (continued)

Nivers	Characteristic		ИНz	40 I	ИНz	50 1	ИНz	66 I	ИНz	11
Num			Max	Min	Max	Min	Max	Min	Max	Unit
B35	A(0:31), BADDR(28:30) to $\overline{\text{CS}}$ valid—as requested by control bit BST4 in the corresponding word in UPM	5.58	_	4.25	_	3.00	_	1.79	_	ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to BS valid—as requested by control bit BST1 in the corresponding word in UPM	13.15	_	10.50	_	8.00		5.58	_	ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to BS valid—as requested by control bit BST2 in the corresponding word in UPM	20.73	_	16.75	_	13.00		9.36	_	ns
B36	A(0:31), BADDR(28:30), and D(0:31) to GPL valid—as requested by control bit GxT4 in the corresponding word in UPM	5.58	_	4.25	_	3.00	_	1.79	_	ns
B37	UPWAIT valid to CLKOUT falling edge ⁹	6.00	_	6.00	_	6.00	_	6.00	_	ns
B38	CLKOUT falling edge to UPWAIT valid ⁹	1.00	_	1.00	_	1.00	_	1.00	_	ns
B39	AS valid to CLKOUT rising edge ¹⁰	7.00	_	7.00	_	7.00	_	7.00	_	ns
B40	A(0:31), TSIZ(0:1), RD/WR, BURST, valid to CLKOUT rising edge	7.00	_	7.00	_	7.00	_	7.00	_	ns
B41	TS valid to CLKOUT rising edge (setup time)	7.00	_	7.00	_	7.00	_	7.00	_	ns
B42	CLKOUT rising edge to TS valid (hold time)	2.00	_	2.00	_	2.00	_	2.00	_	ns
B43	AS negation to memory controller signals negation	_	TBD	_	TBD	_	TBD	_	TBD	ns

¹ Phase and frequency jitter performance results are only valid if the input jitter is less than the prescribed value.

² If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time) then the maximum allowed jitter on EXTAL can be up to 2%.

³ The timings specified in B4 and B5 are based on full strength clock.

⁴ The timing for \overline{BR} output is relevant when the MPC860 is selected to work with external bus arbiter. The timing for \overline{BG} output is relevant when the MPC860 is selected to work with internal bus arbiter.

⁵ The timing required for \overline{BR} input is relevant when the MPC860 is selected to work with internal bus arbiter. The timing for \overline{BG} input is relevant when the MPC860 is selected to work with external bus arbiter.

⁶ The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of the CLKOUT in which the TA input signal is asserted.

⁷ The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of the CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

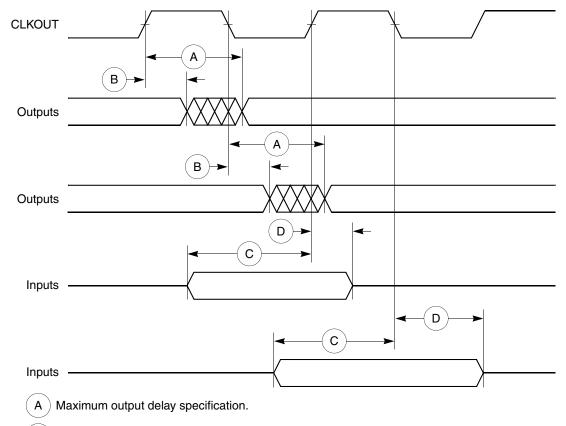
⁸ The timing B30 refers to \overline{CS} when ACS = 00 and to \overline{WE} (0:3) when CSNT = 0.

⁹ The signal UPWAIT is considered asynchronous to the CLKOUT and synchronized internally. The timings specified in B37 and B38 are specified to enable the freeze of the UPM output signals as described in Figure 18.

¹⁰ The $\overline{\text{AS}}$ signal is considered asynchronous to the CLKOUT. The timing B39 is specified in order to allow the behavior specified in Figure 21.



Figure 3 is the control timing diagram.



- (B) Minimum output hold time.
- C Minimum input setup time specification.
- (D) Minimum input hold time specification.

Figure 3. Control Timing

Figure 4 provides the timing for the external clock.

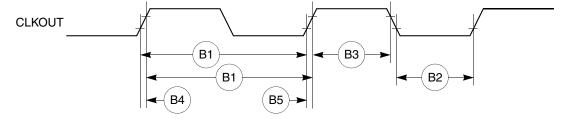


Figure 4. External Clock Timing



Figure 5 provides the timing for the synchronous output signals.

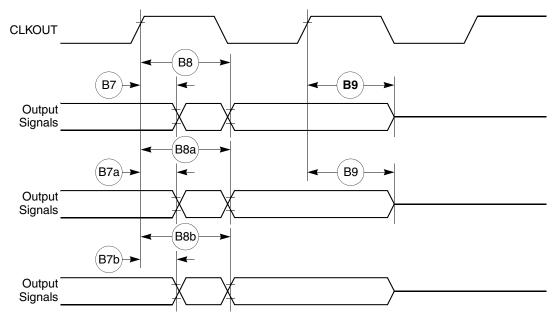


Figure 5. Synchronous Output Signals Timing

Figure 6 provides the timing for the synchronous active pull-up and open-drain output signals.

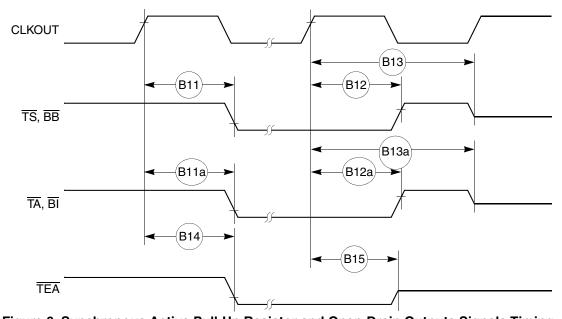


Figure 6. Synchronous Active Pull-Up Resistor and Open-Drain Outputs Signals Timing



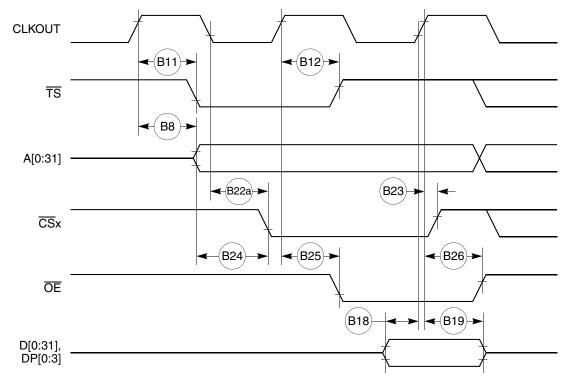


Figure 11. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 10)

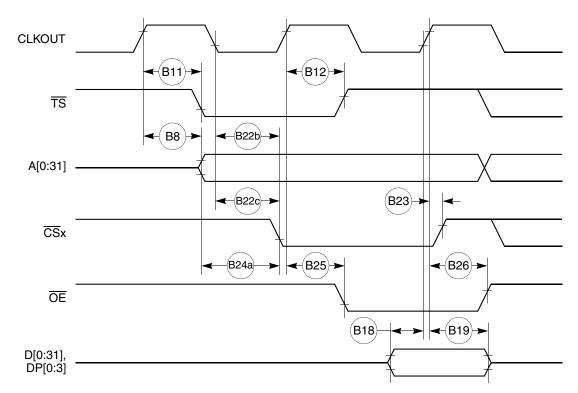


Figure 12. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 11)



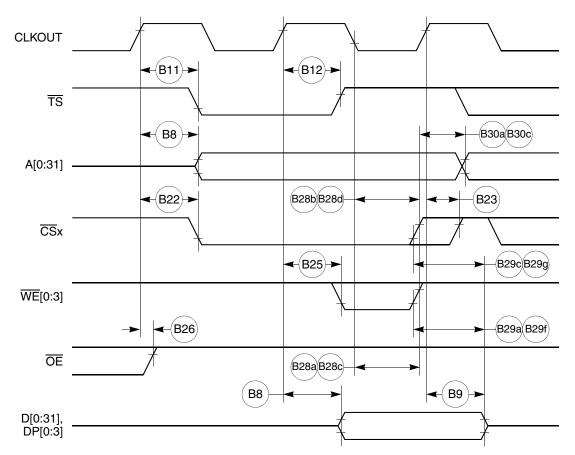


Figure 15. External Bus Write Timing (GPCM Controlled—TRLX = 0 or 1, CSNT = 1)



Figure 17 provides the timing for the external bus controlled by the UPM.

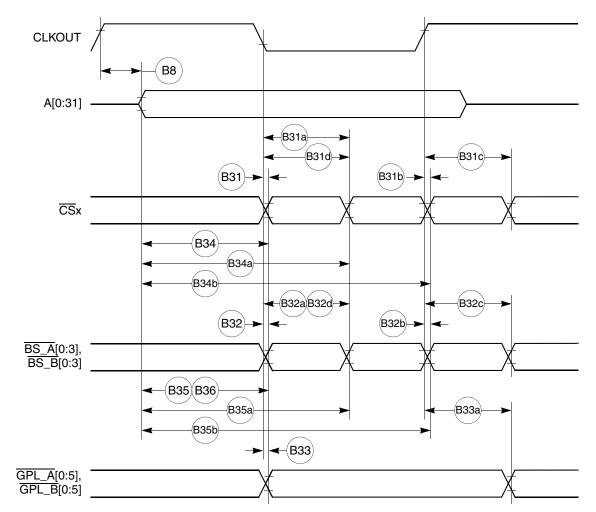


Figure 17. External Bus Timing (UPM Controlled Signals)



Figure 20 provides the timing for the synchronous external master access controlled by the GPCM.

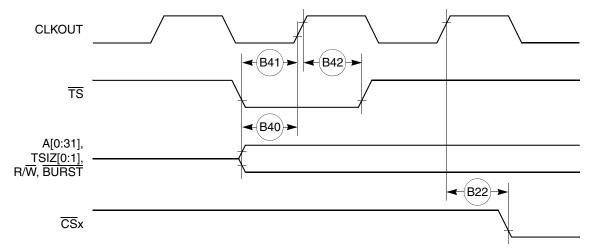


Figure 20. Synchronous External Master Access Timing (GPCM Handled ACS = 00)

Figure 21 provides the timing for the asynchronous external master memory access controlled by the GPCM.

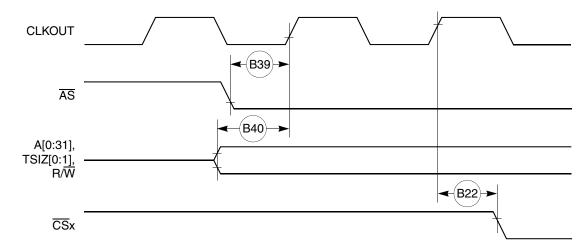


Figure 21. Asynchronous External Master Memory Access Timing (GPCM Controlled—ACS = 00)

Figure 22 provides the timing for the asynchronous external master control signals negation.

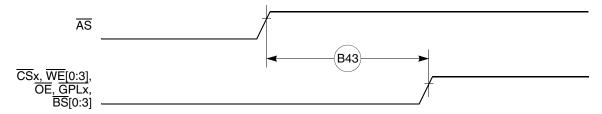


Figure 22. Asynchronous External Master—Control Signals Negation Timing



Table 8 provides interrupt timing for the MPC860.

Table 8. Interrupt Timing

Neves	Characteristic ¹	All Freq	Unit	
Num	Characteristic	Min	Max	Unit
139	IRQx valid to CLKOUT rising edge (setup time)	6.00	_	ns
140	IRQx hold time after CLKOUT	2.00	_	ns
I41	IRQx pulse width low	3.00	_	ns
142	IRQx pulse width high	3.00	_	ns
143	ĪRQx edge-to-edge time	4 × T _{CLOCKOUT}	_	_

The timings I39 and I40 describe the testing conditions under which the IRQ lines are tested when being defined as level-sensitive. The IRQ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT.

The timings I41, I42, and I43 are specified to allow the correct function of the $\overline{\text{IRQ}}$ lines detection circuitry and have no direct relation with the total system interrupt latency that the MPC860 is able to support.

Figure 23 provides the interrupt detection timing for the external level-sensitive lines.

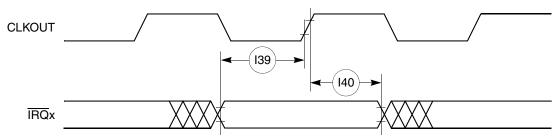


Figure 23. Interrupt Detection Timing for External Level Sensitive Lines

Figure 24 provides the interrupt detection timing for the external edge-sensitive lines.

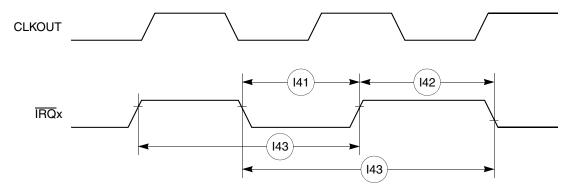


Figure 24. Interrupt Detection Timing for External Edge Sensitive Lines

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Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Norma	Characteristic	33 I	ИНz	40 MHz		50 MHz		66 MHz		Unit
Num		Min	Max	Min	Max	Min	Max	Min	Max	Unit
P44	A(0:31), REG valid to PCMCIA Strobe asserted ¹	20.73	_	16.75	_	13.00	_	9.36	_	ns
P45	A(0:31), REG valid to ALE negation ¹	28.30	_	23.00	_	18.00	_	13.15	_	ns
P46	CLKOUT to REG valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to REG invalid	8.58	_	7.25	_	6.00	_	4.84	_	ns
P48	CLKOUT to CE1, CE2 asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to CE1, CE2 negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to PCOE, IORD, PCWE, IOWR assert time	_	11.00		11.00	_	11.00	_	11.00	ns
P51	CLKOUT to PCOE, IORD, PCWE, IOWR negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	_	15.58		14.25	_	13.00	_	11.84	ns
P54	PCWE, IOWR negated to D(0:31) invalid ¹	5.58	_	4.25	_	3.00	_	1.79	_	ns
P55	WAITA and WAITB valid to CLKOUT rising edge ¹	8.00	_	8.00	_	8.00	_	8.00	_	ns
P56	CLKOUT rising edge to WAITA and WAITB invalid ¹	2.00	_	2.00	_	2.00	_	2.00	_	ns

¹ PSST = 1. Otherwise add PSST times cycle time. PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the \overline{WAITx} signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The $\overline{\text{WAITx}}$ assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, "PCMCIA Interface," in the MPC860 PowerQUICCTM Family User's Manual.

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Figure 34 provides the reset timing for the debug port configuration.

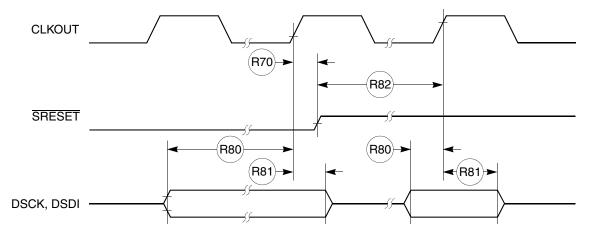


Figure 34. Reset Timing—Debug Port Configuration

10 IEEE 1149.1 Electrical Specifications

Table 13 provides the JTAG timings for the MPC860 shown in Figure 35 through Figure 38.

Table	13.	JTAG	Timing
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Nivers	Characteristic	All Freq	uencies	I I m i h
Num	Characteristic	Min	Max	Unit
J82	TCK cycle time	100.00	_	ns
J83	TCK clock pulse width measured at 1.5 V	40.00	_	ns
J84	TCK rise and fall times	0.00	10.00	ns
J85	TMS, TDI data setup time	5.00	_	ns
J86	TMS, TDI data hold time	25.00	_	ns
J87	TCK low to TDO data valid	_	27.00	ns
J88	TCK low to TDO data invalid	0.00	_	ns
J89	TCK low to TDO high impedance	_	20.00	ns
J90	TRST assert time	100.00	_	ns
J91	TRST setup time to TCK low	40.00	_	ns
J92	TCK falling edge to output valid	_	50.00	ns
J93	TCK falling edge to output valid out of high impedance	_	50.00	ns
J94	TCK falling edge to output high impedance	_	50.00	ns
J95	Boundary scan input valid to TCK rising edge	50.00	_	ns
J96	TCK rising edge to boundary scan input invalid	50.00	_	ns



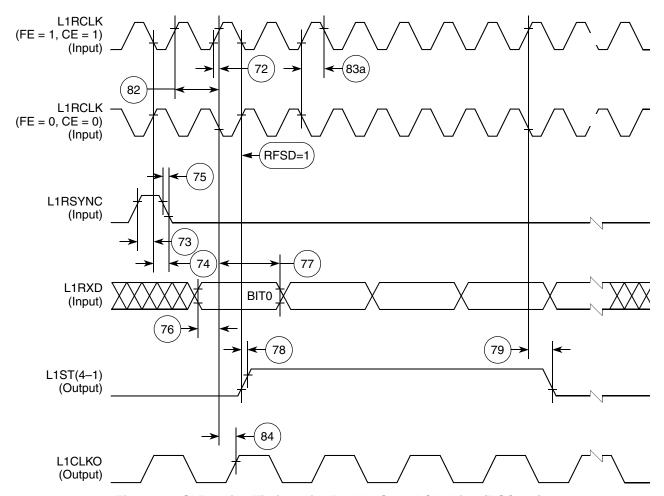


Figure 52. SI Receive Timing with Double-Speed Clocking (DSC = 1)



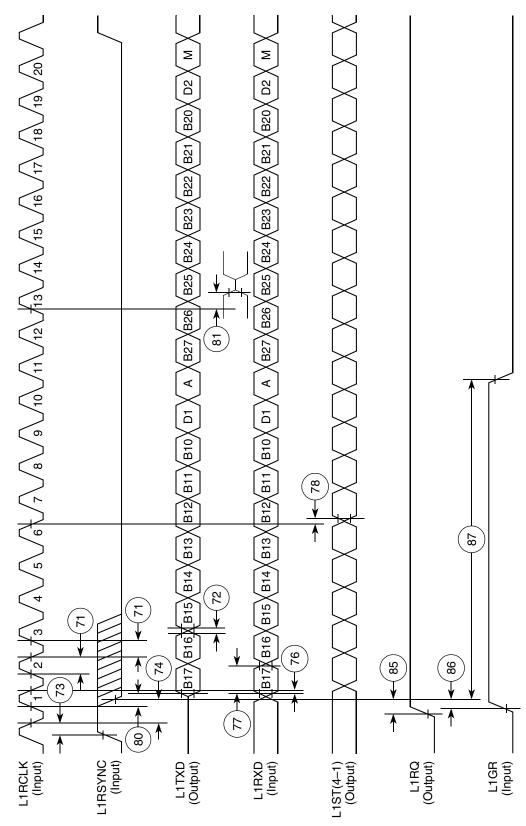


Figure 55. IDL Timing

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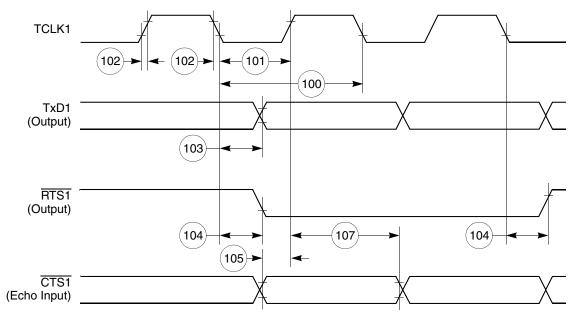


Figure 58. HDLC Bus Timing Diagram

11.8 Ethernet Electrical Specifications

Table 22 provides the Ethernet timings as shown in Figure 59 through Figure 63.

Table 22. Ethernet Timing

N	Characteristic	All Freq	uencies	11
Num	Characteristic	Min	Max	Unit
120	CLSN width high	40	_	ns
121	RCLK1 rise/fall time	_	15	ns
122	RCLK1 width low	40	_	ns
123	RCLK1 clock period ¹	80	120	ns
124	RXD1 setup time	20	_	ns
125	RXD1 hold time	5	_	ns
126	RENA active delay (from RCLK1 rising edge of the last data bit)	10	_	ns
127	RENA width low	100	_	ns
128	TCLK1 rise/fall time	1	15	ns
129	TCLK1 width low	40	_	ns
130	TCLK1 clock period ¹	99	101	ns
131	TXD1 active delay (from TCLK1 rising edge)	10	50	ns
132	TXD1 inactive delay (from TCLK1 rising edge)	10	50	ns
133	TENA active delay (from TCLK1 rising edge)	10	50	ns
134	TENA inactive delay (from TCLK1 rising edge)	10	50	ns



FEC Electrical Characteristics

MII Transmit Signal Timing (MII_TXD[3:0], MII_TX_EN, 13.2 MII_TX_ER, MII_TX_CLK)

The transmitter functions correctly up to a MII TX CLK maximum frequency of 25 MHz +1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII TX CLK frequency – 1%.

Table 30 provides information on the MII transmit signal timing.

Table 30. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	_	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	_	25	
M7	MII_TX_CLK pulse width high	35	65%	MII_TX_CLK period
M8	MII_TX_CLK pulse width low	35%	65%	MII_TX_CLK period

Figure 73 shows the MII transmit signal timing diagram.

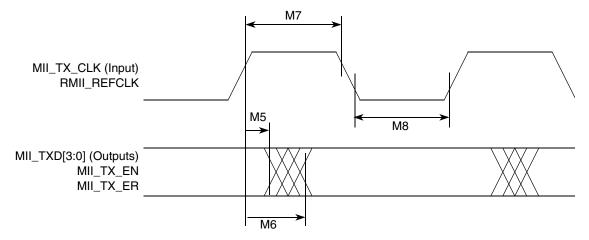


Figure 73. MII Transmit Signal Timing Diagram

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Mechanical Data and Ordering Information

Figure 75 shows the MII serial management channel timing diagram.

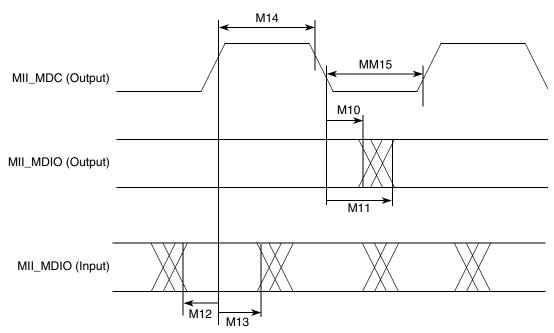


Figure 75. MII Serial Management Channel Timing Diagram

14 Mechanical Data and Ordering Information

14.1 Ordering Information

Table 33 provides information on the MPC860 Revision D.4 derivative devices.

Table 33. MPC860 Family Revision D.4 Derivatives

Device	Number of SCCs ¹	Ethernet Support ² (Mbps)	Multichannel HDLC Support	ATM Support
MPC855T	1	10/100	Yes	Yes
MPC860DE	2	10	N/A	N/A
MPC860DT		10/100	Yes	Yes
MPC860DP		10/100	Yes	Yes
MPC860EN	4	10	N/A	N/A
MPC860SR		10	Yes	Yes
MPC860T		10/100	Yes	Yes
MPC860P		10/100	Yes	Yes

¹ Serial communications controller (SCC)

² Up to 4 channels at 40 MHz or 2 channels at 25 MHz